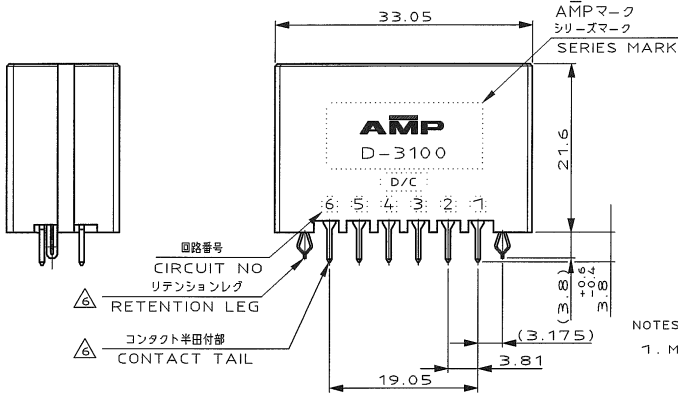
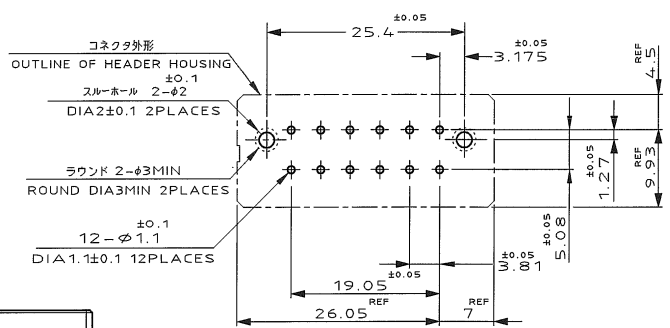
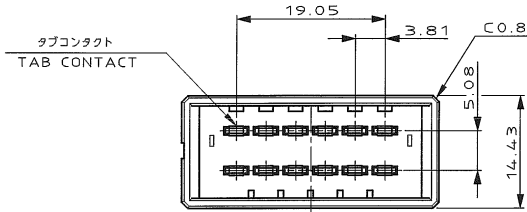


NUMBER 178326



METRIC

PRINT DIST DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT PROJ NO.395-612



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注 記

- 材料: ハウジング: ガラス入り熱可塑性ポリエスチル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38μm MIN めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76μm MIN めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき

△	△	178326-5
△	△	178326-3
△	△	178326-2
(FINISH)		部品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE	CHK.	Y. ISHIKAWA	APP.	S. MANABE
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Copyright © 1995 AMP (Japan) LTD. ALL RIGHTS RESERVED.		WIRE RANGE mm(TAWG) - x		INSULATION DIA mm(φ)		NAME 12 POS DOUBLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100		
B	REVISED	FJDO-0039-03	TSSM	6/27/95	MATERIAL	SEE NOTE	FINISH	SEE NOTE
A	REVISED	FJDO-0112-03	TSSM	5/25/95	DR.	23 JUN 95	DE.	23 JUN 95
0	RELEASED	FJDO-2528-95	NM	6/30/95	DR.	N. Matsuyama	DE.	N. Matsuyama

Tyco Electronics		Tyco Electronics AMP K.K. Kawasaki, Japan		
(GENERAL TOLERANCE)		SIZE	LOC	NUMBER
100% ±0.3		A3	J	C-178326
100% ±0.4		SCALE	REV.	SHEET
200% ±0.45		2-1	B	1 OF 1

(CUSTOMER DRAWING) 顧客用図面